

Amendments to the Claims:

This listing of claims will replace all prior versions and listings of claims in the application.

Listing of Claims:

1. (Original) A chip type LED comprising an insulating substrate, a light emitting diode chip mounted on an upper surface of the insulating substrate, and a transparent package provided on the upper surface of the insulating substrate to seal the light emitting diode chip,

wherein the light emitting diode chip is mounted on the upper surface of the insulating substrate with an anode electrode of the chip oriented downward and with a cathode electrode of the chip oriented upward.

2. (Original) The chip type LED according to claim 1, wherein the light emitting diode chip further includes a light emitting layer arranged adjacent to the cathode electrode of the chip and also includes a side surface inclined inwardly as the side surface extends from the cathode electrode toward the anode electrode.

3. (Currently Amended) The chip type LED according to claim 1 or 2, wherein the upper surface of the insulating substrate is white at least around the light emitting diode chip.